

Bluetooth LE microcomputer / module

Bluetooth qualification acquisition

Introduction

This document describes how to acquire *Bluetooth*[®] qualification for a product with a Bluetooth Low Energy (hereinafter Bluetooth LE) technology compatible microcomputer (hereinafter "IC") or a product with a module mounted with IC (hereinafter "Module").

Target Device

- IC
 - RX23W Group
 - RA4W1 Group
 - RE01B Group
 - RL78/G1D Group
- Module
 - RX23W Module
 - RY7011 (RL78/G1D mounted)

Note: This document will be a possibility that the contents change with a renewal in Bluetooth SIG website and change in the Bluetooth Qualification Program from now on.

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1. Overview

This application note describes how to register (Declaration) a product using a Qualified Design Identification number (QDID) of our qualified design when selling a device equipped with a IC or Module as a Bluetooth products.

Bluetooth SIG prescribes that it is necessary to satisfy the giving requirements of Bluetooth license to sell a product using Bluetooth technology and a trademark. Please confirm the governance document with the following URL for details.

<https://www.bluetooth.com/about-us/governing-documents>

1.1 QDID of acquired qualified design

Figure 1-1 descriptions the composition of each product type of our qualified design.

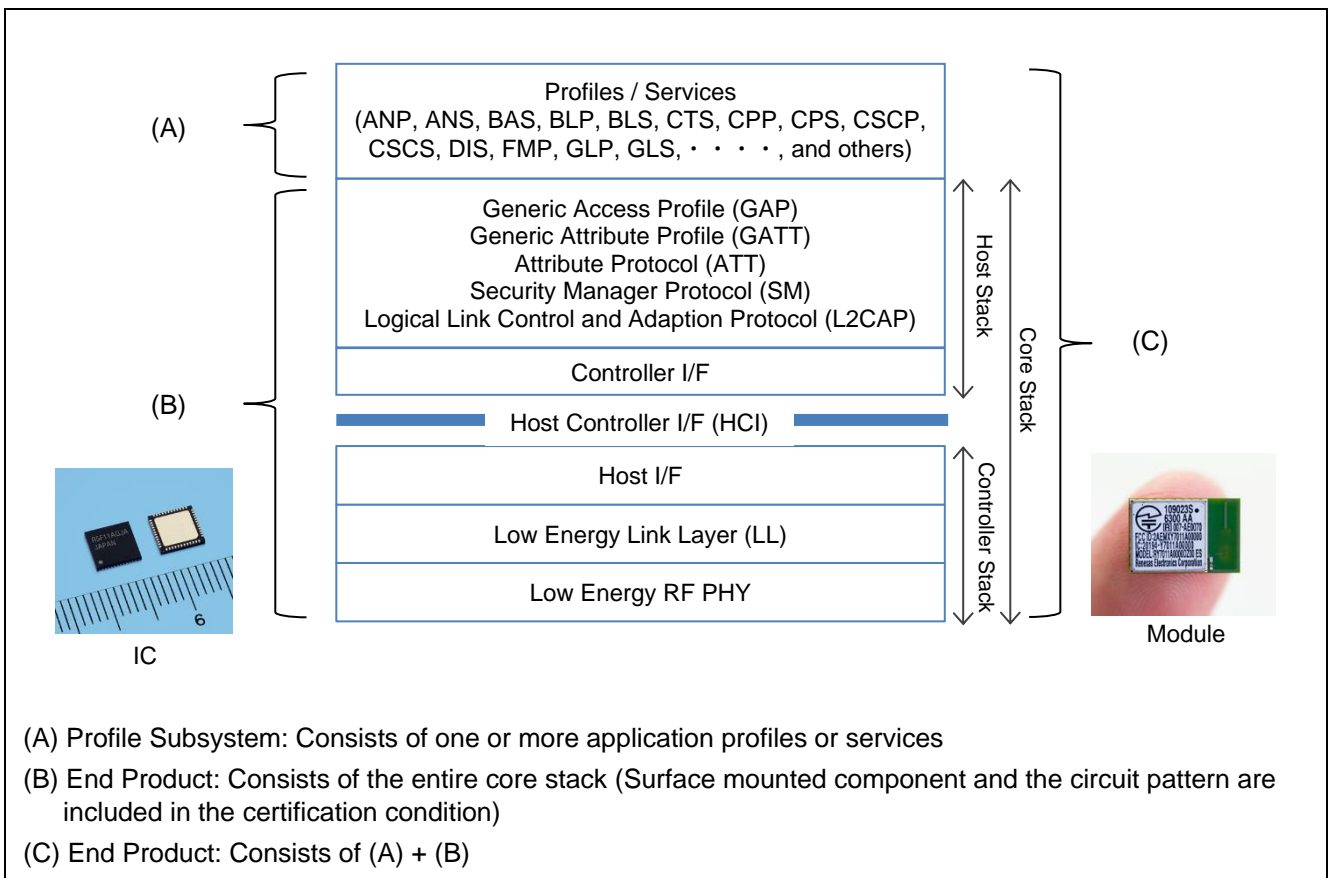


Figure 1-1 Product type composition

Table 1-1 to Table 1-5 descriptions the list of the acquired qualified design that can be used for each of our ICs and Modules. please refer to "3. Product Registration (Declaration)" for how to use the acquired qualified design.

Table 1-1 Acquired qualified design for RX23W Group and RX23W Module

Qualified Design ID (QDID)	Design Name	Product Type	Spec Name	Listing Date
134349	rBLE50A - Core Stack	End Product	5.0	2019-11-01
134484 (*1)	rBLEx - GATT Profile Set 01	Profile Subsystem	N/A	2019-11-01
134527	rBLEx - Mesh 1.01	Profile Subsystem	N/A	2019-11-01
199248	rBLEx - GATT Profile Set 2212	Profile Subsystem	N/A	2022-12-27

Table 1-2 Acquired qualified design for RA4W1 Group

Qualified Design ID (QDID)	Design Name	Product Type	Spec Name	Listing Date
134349	rBLE50A - Core Stack	End Product	5.0	2019-11-01
134484 (*1)	rBLEx - GATT Profile Set 01	Profile Subsystem	N/A	2019-11-01
134527	rBLEx - Mesh 1.01	Profile Subsystem	N/A	2019-11-01
199248	rBLEx - GATT Profile Set 2212	Profile Subsystem	N/A	2022-12-27

Table 1-3 Acquired qualified design for RE01B Group

Qualified Design ID (QDID)	Design Name	Product Type	Spec Name	Listing Date
134349	rBLE50A - Core Stack	End Product	5.0	2019-11-01
134484 (*3)	rBLEx - GATT Profile Set 01	Profile Subsystem	N/A	2019-11-01

Table 1-4 Acquired qualified design for RL78/G1D Group

Qualified Design ID (QDID)	Design Name	Product Type	Spec Name	Listing Date
122047	R5F11Axxxxx - Core Stack	End Product	5.0 (*4)	2019-01-15
78971 (*2)	Renesas SMART Profiles	Profile Subsystem	N/A	2016-01-19
97611 (*3)	Renesas SMART Profiles A-01	Profile Subsystem	N/A	2017-06-16

Table 1-5 Acquired qualified design for RL78/G1D Group

Qualified Design ID (QDID)	Design Name	Product Type	Spec Name	Listing Date
122047	R5F11Axxxxx - Core Stack	End Product	5.0 (*4)	2019-01-15
97611 (*3)	Renesas SMART Profiles A-01	Profile Subsystem	N/A	2017-06-16

Notes: *1. After February 1, 2023, this QDID cannot be used for product registration (Declaration). Please use QDID 199248 (rBLEx - GATT Profile Set 2212) for new product registration.

*2. After February 1, 2022, this QDID cannot be used for product registration (Declaration). After February 1, 2023, you will not be able to do anything other than sell of qualified products.

*3. After February 1, 2023, this QDID cannot be used for product registration (Declaration). After February 1, 2024, you will not be able to do anything other than sell of qualified products.

*2,3. If you do not support the profile specifications formulated by the Bluetooth SIG, or if you use only the "Custom Profile" specified by the manufacturer self, you can register (Declaration) the product without using these QDIDs.

*4. Optional functions added to Core Specification 4.2 or later are not supported.

1.2 Support Profiles / Services

Table 1-6 descriptions the profiles and services supported by each Profile Subsystem.

Table 1-6 Support Profiles / Services

Profile / Service		QDID				
		78971	97611	134484	134527	199248
ANP 1.0	Alert Notification Profile 1.0	●		●		●
ANS 1.0	Alert Notification Service 1.0	●		●		●
AIOP 1.0	Automation IO Profile 1.0			●		●
AIOS 1.0	Automation IO Service 1.0			●		●
BAS 1.0	Battery Service 1.0	●		●		●
BCS 1.0	Body Composition Service 1.0			●		●
BLP 1.0	Blood Pressure Profile 1.0	●				
BLP 1.0.1	Blood Pressure Profile 1.0.1			●		
BLP 1.1.1	Blood Pressure Profile 1.1.1					●
BLS 1.0	Blood Pressure Service 1.0	●		●		
BLS 1.1.1	Blood Pressure Service 1.1.1					●
BMS 1.0	Bond Management Service 1.0			●		
BMS 1.0.1	Bond Management Service 1.0.1					●
BSP 1.0	Binary Sensor Profile 1.0					
BSS 1.0	Binary Sensor Service 1.0					
CGMP 1.0	Continuous Glucose Monitor Profile 1.0					
CGMP 1.0.1	Continuous Glucose Monitor Profile 1.0.1			●		
CGMP 1.0.2	Continuous Glucose Monitor Profile 1.0.2					●
CGMS 1.0	Continuous Glucose Monitor Service 1.0					
CGMS 1.0.1	Continuous Glucose Monitor Service 1.0.1			●		

Profile / Service		QDID				
		78971	97611	134484	134527	199248
CGMS 1.0.2	Continuous Glucose Monitor Service 1.0.2					●
CPP 1.0	Cycling Power Profile 1.0	●				
CPP 1.1	Cycling Power Profile 1.1			●		●
CPS 1.0	Cycling Power Service 1.0	●				
CPS 1.1	Cycling Power Service 1.1			●		●
CSCP 1.0	Cycling Speed and Cadence Profile 1.0	●		●		●
CSCS 1.0	Cycling Speed and Cadence Service 1.0	●		●		●
CTS 1.0	Current Time Service 1.0	●				
CTS 1.1	Current Time Service 1.0			●		●
DIS 1.0	Device Information Service 1.0					
DIS 1.1	Device Information Service 1.1	●		●		●
EMP 1.0	Emergency Profile 1.0					
EMCS 1.0	Emergency Configuration Service 1.0					
ESP 1.0	Environmental Sensing Profile 1.0			●		●
ESS 1.0	Environmental Sensing Service 1.0			●		●
FMP 1.0	Find Me Profile 1.0	●		●		●
FTMP 1.0	Fitness Machine Profile 1.0			●		●
FTMS 1.0	Fitness Machine Service 1.0			●		●
GLP 1.0	Glucose Profile 1.0	●		●		
GLP 1.0.1	Glucose Profile 1.0.1					●
GLS 1.0	Glucose Service 1.0	●		●		
GLS 1.0.1	Glucose Service 1.0.1					●
HOGP 1.0	HID over GATT Profile 1.0	●		●		●
HIDS 1.0	HID Service 1.0	●		●		●
HPS 1.0	HTTP Proxy Service 1.0					
HRP 1.0	Heart Rate Profile 1.0	●		●		●
HRS 1.0	Heart Rate Service 1.0	●		●		●
HTP 1.0	Health Thermometer Profile 1.0	●		●		●
HTS 1.0	Health Thermometer Service 1.0	●		●		●
IAS 1.0	Immediate Alert Service 1.0	●		●		●
IDS 1.0	Insulin Delivery Service 1.0			●		
IDS 1.0.1	Insulin Delivery Service 1.0.1					●
IDP 1.0	Insulin Delivery Profile 1.0			●		
IDP 1.0.1	Insulin Delivery Profile 1.0.1					●
IPS 1.0	Indoor Positioning Service 1.0					
IPSP 1.0	Internet Protocol Support Profile 1.0					

Profile / Service		QDID				
		78971	97611	134484	134527	199248
LLS 1.0	Link Loss Service 1.0	●				
LLS 1.0.1	Link Loss Service 1.0.1			●		●
LNP 1.0	Location and Navigation Profile 1.0	●		●		●
LNS 1.0	Location and Navigation Service 1.0	●		●		●
NDCS 1.0	Next DST Change Service 1.0	●		●		●
OTP 1.0	Object Transfer Profile 1.0					
OTS 1.0	Object Transfer Service 1.0					
PASP 1.0	Phone Alert Status Profile 1.0	●		●		●
PASS 1.0	Phone Alert Status Service 1.0	●		●		●
PLXP 1.0	Pulse Oximeter Profile 1.0		●	●		
PLXP 1.0.1	Pulse Oximeter Profile 1.0.1					●
PLXS 1.0	Pulse Oximeter Service 1.0		●	●		
PLXS 1.0.1	Pulse Oximeter Service 1.0.1					●
PXP 1.0	Proximity Profile 1.0	●				
PXP 1.0.1	Proximity Profile 1.0.1			●		●
RCP 1.0	Reconnection Configuration Profile 1.0			●		
RCP 1.0.1	Reconnection Configuration Profile 1.0.1					●
RCS 1.0	Reconnection Configuration Service 1.0			●		
RCS 1.0.1	Reconnection Configuration Service 1.0.1					●
RSCP 1.0	Running Speed and Cadence Profile 1.0	●		●		●
RSCS 1.0	Running Speed and Cadence Service 1.0	●		●		●
RTUS 1.0	Reference Time Update Service 1.0	●		●		●
SCPP 1.0	Scan Parameters Profile 1.0	●		●		●
SCPS 1.0	Scan Parameters Service 1.0	●		●		●
TDS 1.0	Transport Discovery Service 1.0					
TIP 1.0	Time Profile 1.0	●		●		●
TPS 1.0	TX Power Service 1.0	●		●		●
UDS 1.0	User Data Service 1.0			●		
UDS 1.1	User Data Service 1.1					●
WSP 1.0	Weight Scale Profile 1.0			●		●
WSS 1.0	Weight Scale Service 1.0			●		●
MESH 1.0	Mesh Profile 1.0					
MESH 1.0.1	Mesh Profile 1.0.1				●	
MMDL 1.0	Mesh Model 1.0					
MMDL 1.0.1	Mesh Model 1.0.1				●	

2. Common operation

It is describes about necessary common operation to acquire Bluetooth qualification.

2.1 Bluetooth SIG Members registration and acquisition of personal account

Member registration to SIG is needed to use a license of Bluetooth and the brand. Operation on the web necessary to qualification acquisition and product registration (Declaration) becomes possible after member registration. This application note describes registration of "Adopter" member class.

2.1.1 Register the company to members of Bluetooth SIG (no charge)

- (1). Display the following URL by the browser. Click the [Apply for Adopter Membership] button at the middle of the displayed [Become a Bluetooth SIG Member] page.

<https://www.bluetooth.com/develop-with-bluetooth/join>

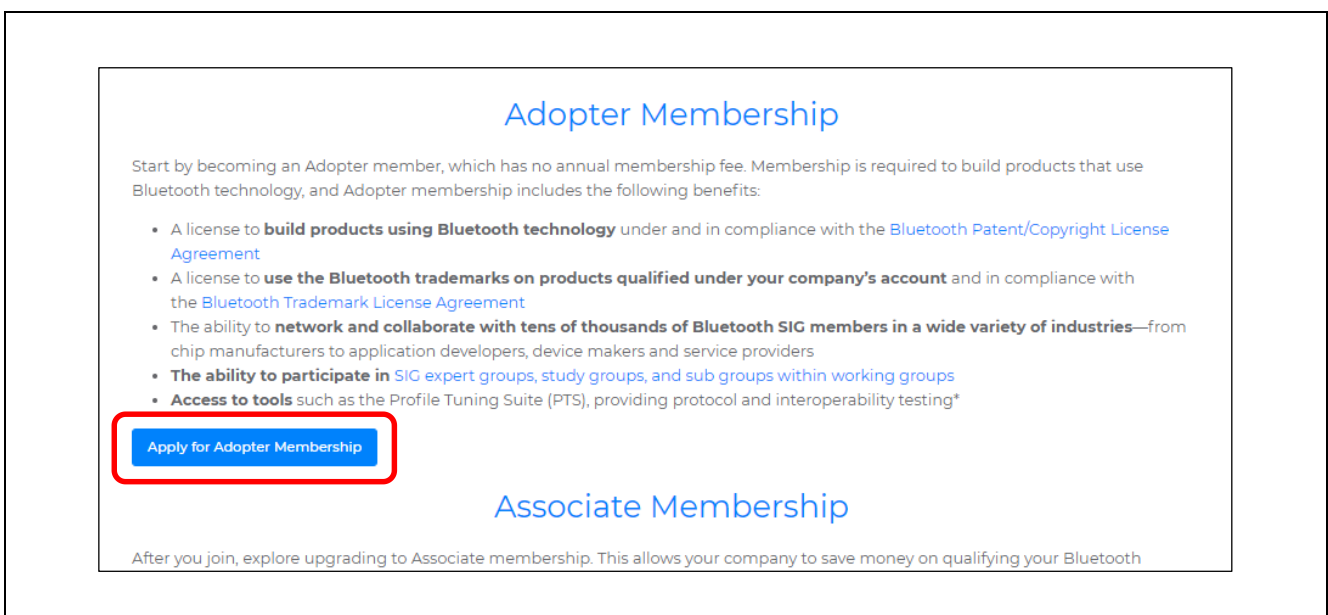


Figure 2-1 [Apply for Adopter Membership] button

- (2). Since the application page for Bluetooth SIG membership will be displayed, please check the details on the preparation described in [① Prepare your application materials].

- Copy of corporate registration (PDF).
- Power of attorney

If the applicant is different from the representative of the company, you may be asked for a power of attorney. Please prepare a letter of attorney in English that you can confirm that you have the authority to sign on behalf of the representative of the company. There is no official template, but the signature of the representative is mandatory.

- (3). Select the country with [★ Start Here:] at the bottom of the same page, enter the applicant's Email address, and click the [Start Membership Application] button to display the form input page.]

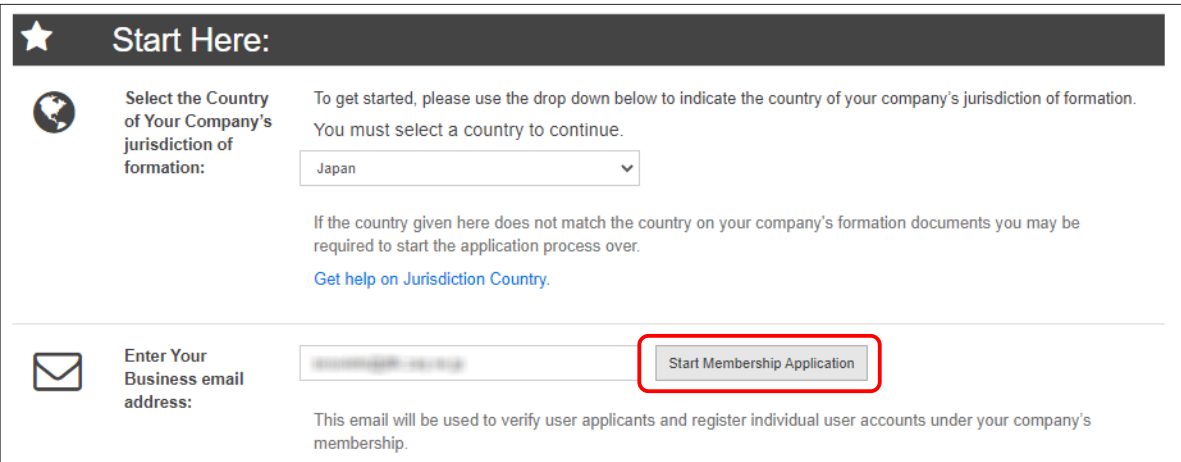


Figure 2-2 [Start Membership Application] button

- (4). Check the contents of the displayed form and enter necessary information.

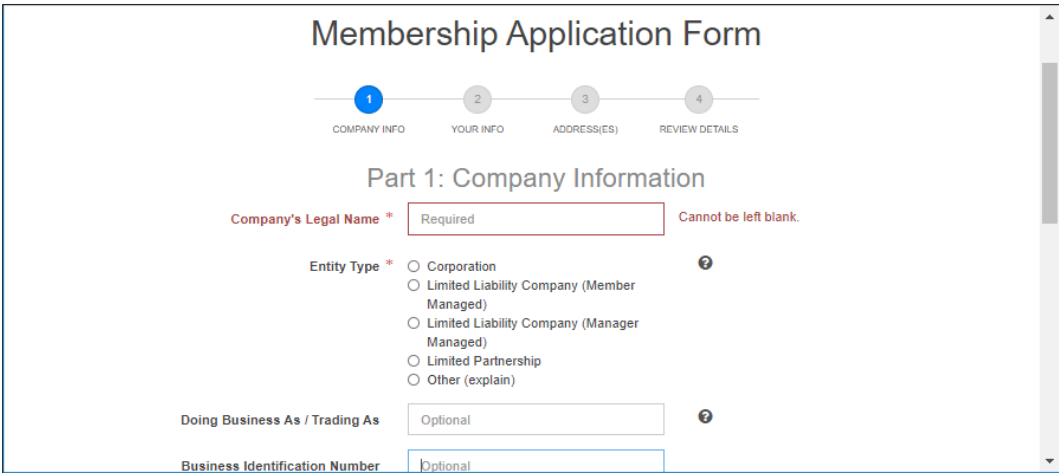
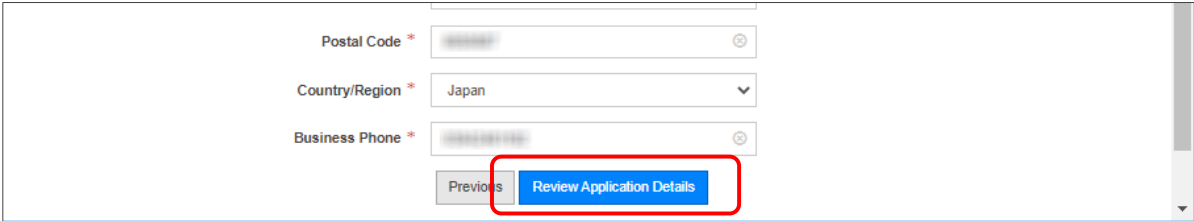


Figure 2-3 Form input page

The form will be displayed in the order of [Part 1: Company Information] → [Part 2: My Information] → [Part 3: Office Locations].

For [Company's Legal Name] in [Part 1: Company Information], enter the name stated in the copy of corporate registration. [Company's Formation Documents] will upload the PDF file of the copy of corporate registration.

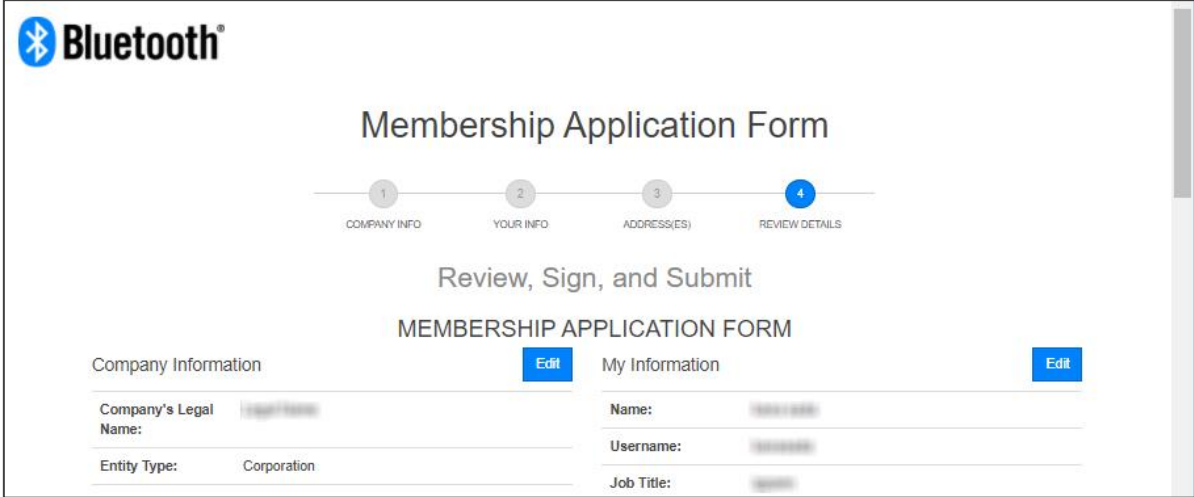
When you have completed all forms, click the [Review Application Details] button under the [Part 3: Office Locations] form to display the [Review, Sign, and Submit] page.



The screenshot shows a form with three input fields: 'Postal Code *', 'Country/Region *' (set to 'Japan'), and 'Business Phone *'. Below these fields are two buttons: 'Previous' and 'Review Application Details'. The 'Review Application Details' button is highlighted with a red rectangular box.

Figure 2-4 [Review Application Details] button

(5). When the [Review, Sign, and Submit] page is displayed, confirm the input contents.



The screenshot displays the 'Bluetooth' logo at the top left. The main heading is 'Membership Application Form'. Below this is a progress indicator with four steps: 1. COMPANY INFO, 2. YOUR INFO, 3. ADDRESS(ES), and 4. REVIEW DETAILS. The fourth step is highlighted with a blue circle. The main heading for this page is 'Review, Sign, and Submit'. Below this is the title 'MEMBERSHIP APPLICATION FORM'. The form is divided into two sections: 'Company Information' and 'My Information'. Each section has an 'Edit' button. The 'Company Information' section includes fields for 'Company's Legal Name' and 'Entity Type' (set to 'Corporation'). The 'My Information' section includes fields for 'Name', 'Username', and 'Job Title'.

Figure 2-5 [Review, Sign, and Submit] page

(6). If there is no error in the input content, move to the [Signature and Submission] below than middle of the page, confirm the contents of the declaration statement of the membership agreement, check the check box at the beginning.

Signature and Submission

kana sada ("Signing Agent") is the ippann of Legal Name ("Applicant Company"). By typing his or her name or other symbol of Signing Agent's signature in the Signature Field below, Signing Agent:

- Personally certifies that the above information is true and correct, and Signing Agent has corrected any errors in the above information by using the "Edit" buttons;
- Represents and warrants that Signing Agent has been duly authorized to submit this Membership Application on behalf of Applicant Company; and that Signing Agent has read, fully understands, and is duly authorized to bind Applicant Company to each of the following hyperlinked agreements (collectively, the "Membership Agreements"): (1) the Bluetooth SIG Membership Commitment Agreement, (2) the Bluetooth SIG Patent/Copyright License Agreement, and (3) the Bluetooth SIG Trademark License Agreement.
- Represents and warrants that Applicant Company does not, by its governing documents or other applicable law, require more than one signatory, a company stamp or seal, or a witnessed signature in order to be legally bound to the Membership Agreements.
- Agrees on behalf of Signing Agent and Applicant Company to contract in English and electronically, adopts the characters or symbols input in the signature field below as Signing Agent's signature, with the same effect as an ink signature, and electronically signs each of the Membership Agreements.
- Agrees, on behalf of Applicant Company, that Applicant Company will comply with the Membership Agreements.
- Agrees to the Bluetooth SIG Terms of Use ("TOU") and that all use of any account issued to Signing Agent by Bluetooth SIG and Bluetooth SIG's websites and all applications, databases, software, plug-ins, test scripts, tools, and services that Signing Agent may access with his or her user account is subject to and will be in compliance with the TOU, the Membership Agreements, and all other policies and procedures of Bluetooth SIG.
- Certifies that Signing Agent understands that the Membership Application Form is an offer by Applicant Company to enter into the Membership Agreements that may be accepted or rejected by Bluetooth SIG in its sole discretion and that Applicant Company will not become a member and Bluetooth SIG has not entered into the Membership Agreements with Applicant Company until Signing Agent receives a written notification (which may be by email) from Bluetooth SIG that Applicant Company's application has been accepted and membership issued.

If any of the foregoing is not correct or Signing Agent does not agree and certify to the foregoing, Signing Agent must exit the Membership Application Form without signing.

Figure 2-6 [Signature and Submission]

Finally sign the [Signature] text box under the declaration and click the [Signature Confirmed - Submit Application] button to complete the online process.

If any of the foregoing is not correct or Signing Agent does not agree and certify to the foregoing, Signing Agent must exit the Membership Application Form without signing.

Legal Name

Signature:

By:

Its:

Date: 2021-04-26

Figure 2-7 [Signature Confirmed - Submit Application] button

When the application is accepted, the applicant will receive an Email from the person in charge of the Bluetooth SIG, so please submit a power of attorney if requested.

2.1.2 Acquisition of the account of the member company's employee (no charge)

- (1). Display the following URL by the browser. Click the [Click here] button of the [Employee User Accounts] at the bottom of the displayed page.

<https://www.bluetooth.com/develop-with-bluetooth/join>

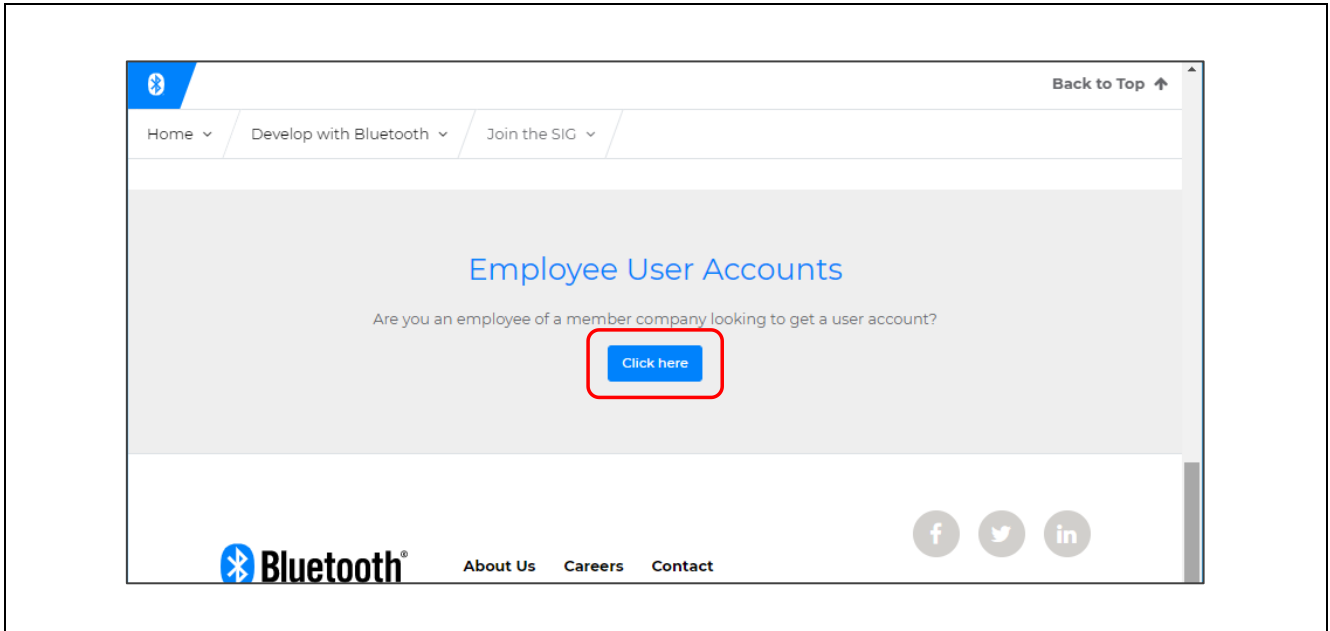


Figure 2-8 Apply for employee user account

- (2). In the text box on the displayed the [User Account Application] page, enter the Email address of the employee who applies for the account and click the [Submit Email Address] button.

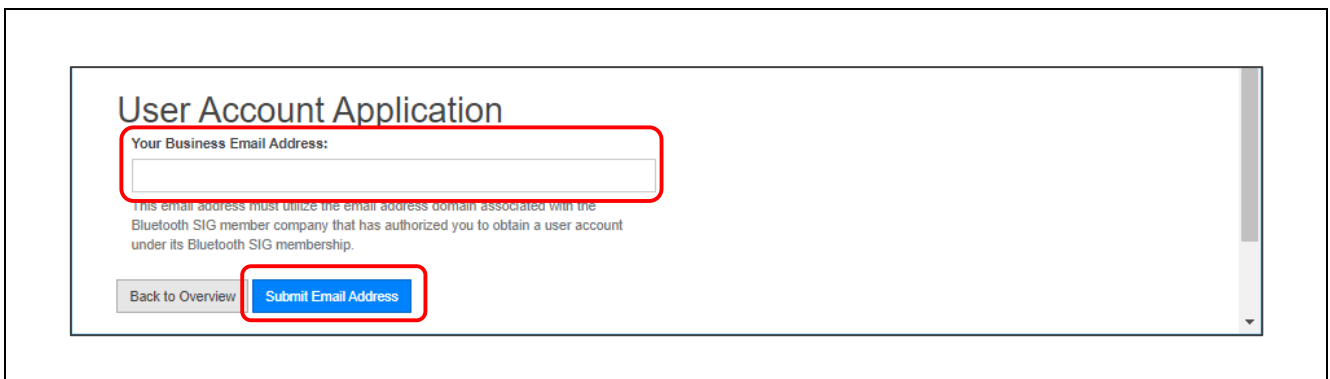


Figure 2-9 [User Account Application] page

- (3). A registration confirmation Email will be sent from the Bluetooth SIG to the account applicant. Click on the URL listed in the Email and enter the "My Information" on the opened WEB page.
- (4). After completing the entry you will receive an Email asking for the creation of a password so please access the URL stated in the Email and complete the creation of the password. Acquisition of the employee's user account is complete with this.

(5). By clicking the [Login] at the upper left of <<https://www.bluetooth.com>> and entering the user name and password on the [Log In] page opened, you will be accessible to the member page.

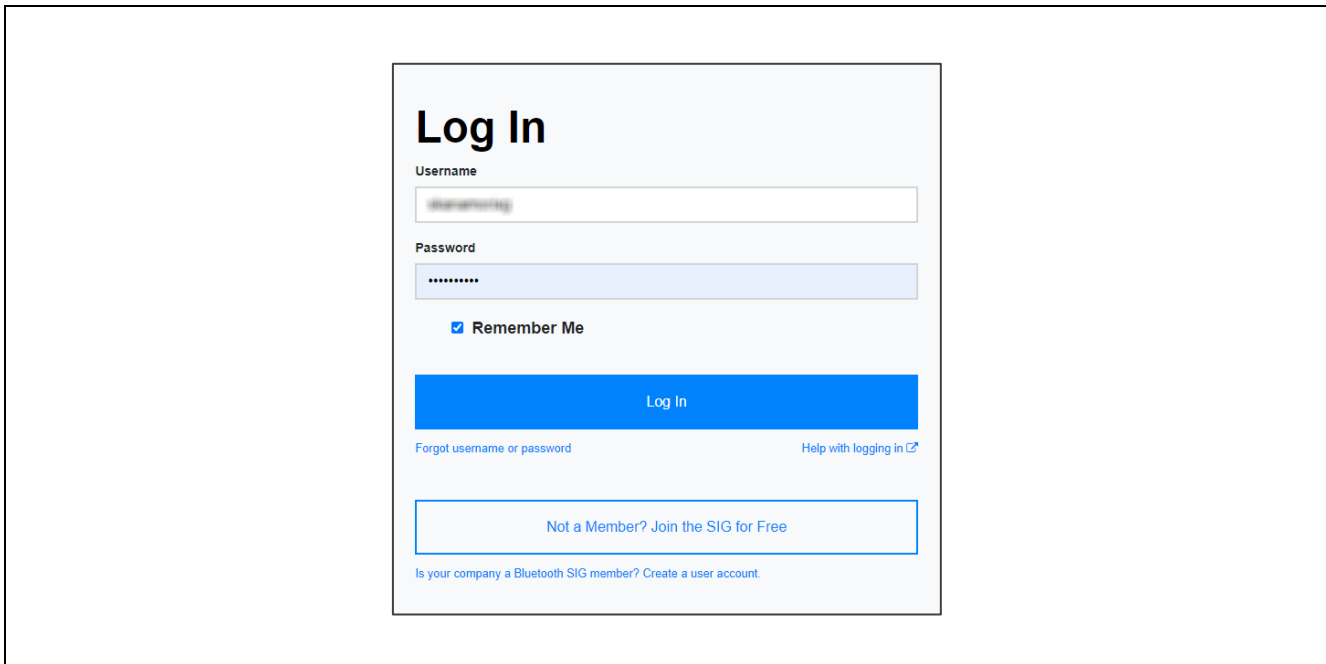


Figure 2-10 [Log In] page

2.2 Purchase of Declaration ID

When product registering (Declaration) by referring to the Qualified design, it is necessary to purchase Declaration ID. Below is the Web operation when the application company pays purchase cost directly to Bluetooth SIG.

Notes: 1. When requesting remittance to a certification body, please follow the instructions of the certification body.

2. For the purchase procedure, please use the same user account as "3. Product Registration (Declaration)" described later.

(1). After login to <<https://www.bluetooth.com>>, starting the Launch Studio from the following URL and select the [Manage Declaration IDs] tab.

<https://launchstudio.bluetooth.com>

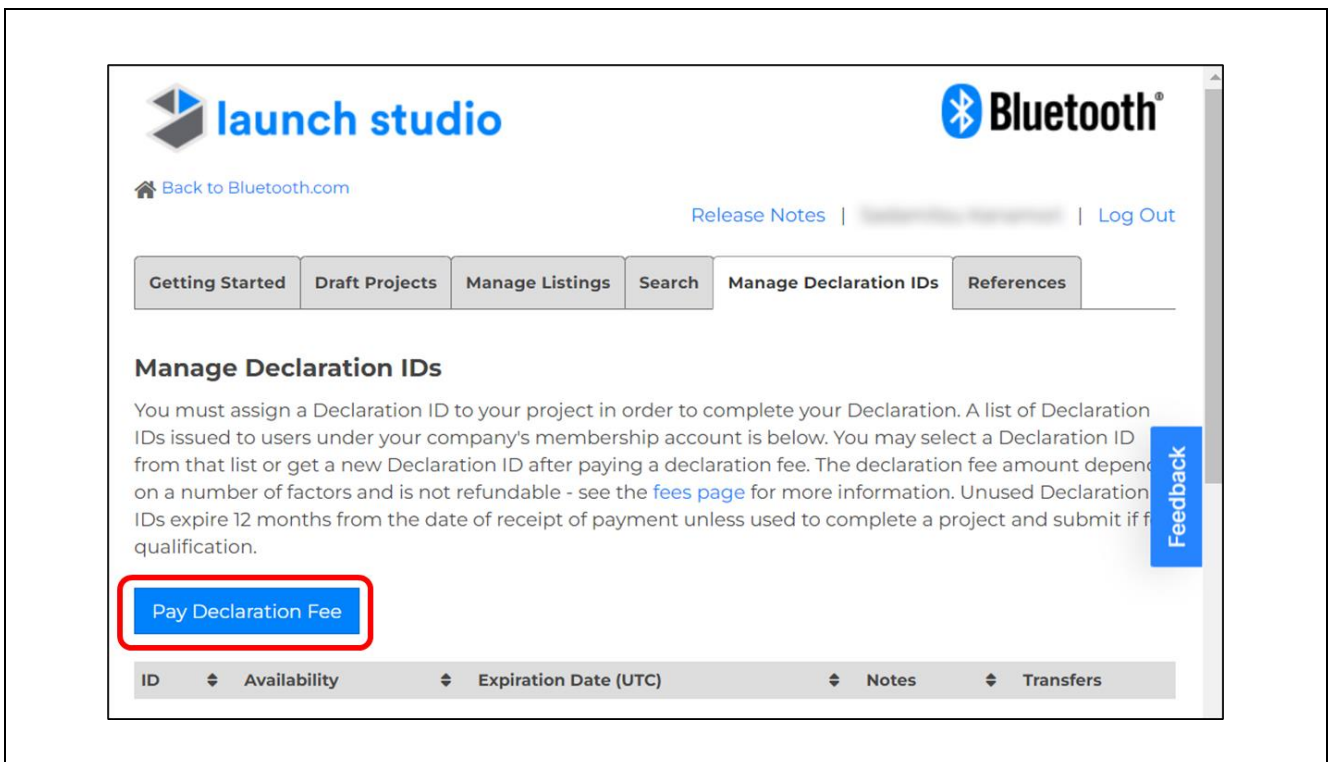


Figure 2-11 [Manage Declaration IDs] tab

Click the "[fees page](#)" in the description to see the price of the Declaration ID.

Click the [Pay Declaration Fee] button on the left side to display the [Pay Declaration Fee] panel.

(2). Enter necessary items to the displayed [Pay Declaration Fee] panel.

- Select [Standard] for [Declaration Type].
- Enter "1" in [Quantity].

- In [Payment Method], select [Credit Card] or [Invoice]. The following input items change according to the selection contents of [Payment Method], so please enter the necessary items for each. Items related to company address are automatically entered from user account information.

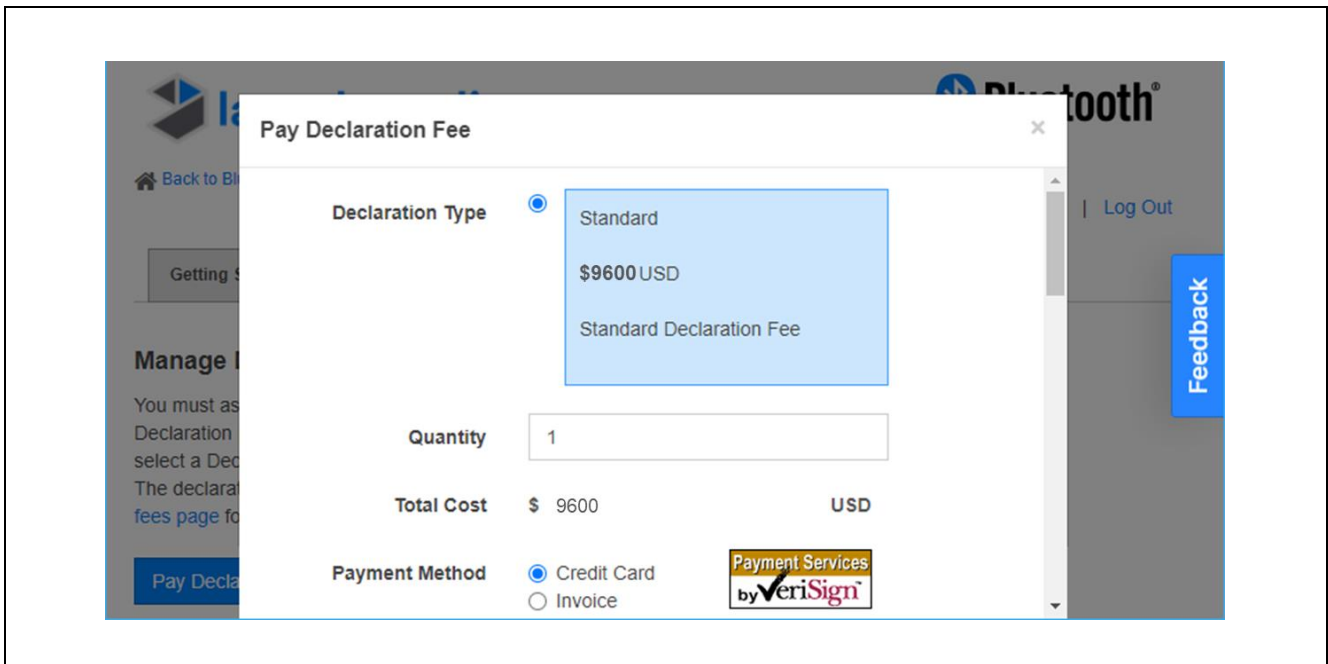


Figure 2-12 [Pay Declaration Fee] panel

- (3). When all input is completed, click the completion button at the bottom of the panel. The completion button changes depending on the item selected in [Payment Method]. When [Credit Card] is selected, it becomes [Pay Declaration Fee], and if you select [Invoice] it will be [Create Invoice]. The payment procedure when [Credit Card] is selected is now complete.

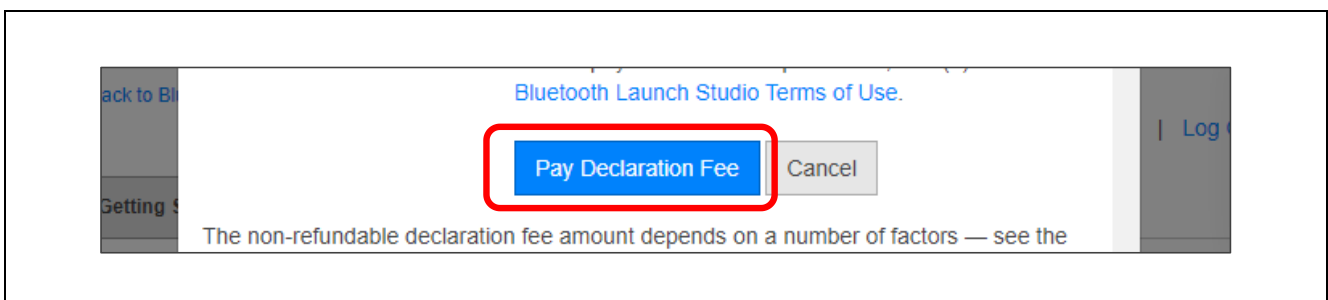


Figure 2-13 [Pay Declaration Fee] button

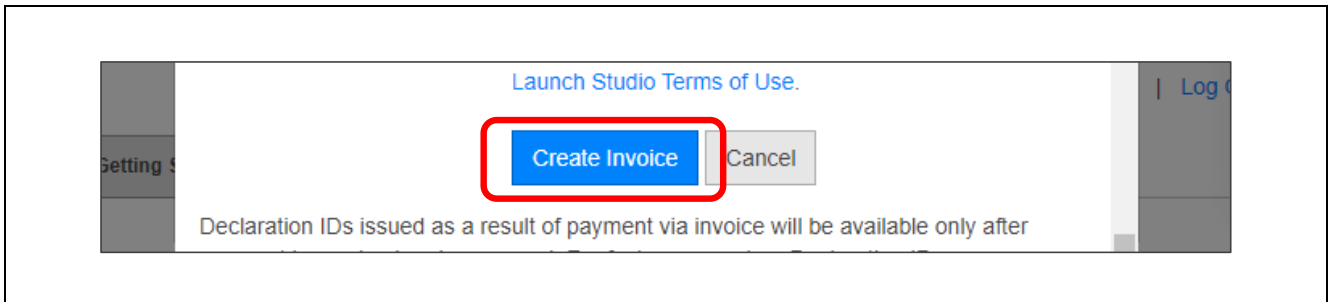


Figure 2-14 [Create Invoice] button

Click on the [Create Invoice] button to open Invoice PDF file and save it. (The same invoice is also attached to the Email sent from the Bluetooth SIG to the Invoice applicant.)

Please make overseas remittance procedure to the account described in Invoice.

Note: Please write Invoice number "INVxxxxx" of the top right of the Invoice in the telegram (message) column of the overseas remittance request form submit to the bank. If this number is not described, Issuance destination of the Declaration ID becomes the unknown.

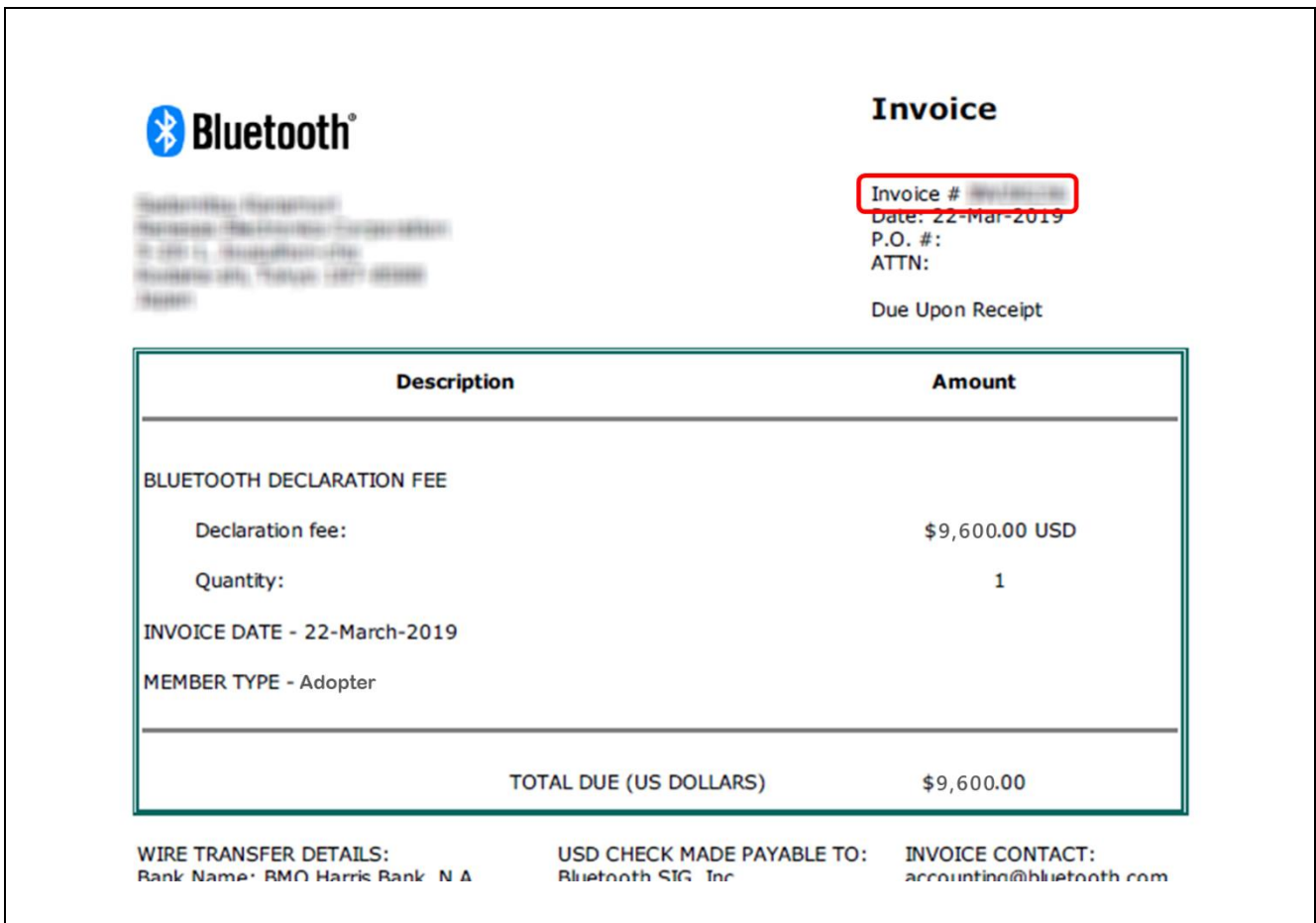


Figure 2-15 Invoice sample

You can confirm the Declaration ID you purchased on the [Manage Declaration IDs] tab of the Launch Studio.

3. Product Registration (Declaration)

3.1 Perform RF-PHY test (IC Implement device only)

When Implement the IC, the characteristics may change due to design modification of RF part. Perform the RF-PHY test with the Bluetooth Qualification Test Facility (BQTF) in the following procedure, prove that there are no problems in the characteristics, and then register the product.

(1). Ask BQTF for RF-PHY test and Bluetooth Qualification Consultants (BQC) support.

Select BQTF from the following URL.

<https://www.bluetooth.com/develop-with-bluetooth/qualification-listing/qualification-test-facilities>

When ask to BQTF submit the following information.

- Business card information of client
- Company's Bluetooth SIG member class (Adopter / Associate)
- Qualified design ID of implemented IC (QDID)
The QDIDs that correspond to the Core specifications of each IC are as follows.

Table 3-1 QDID of our company IC

IC	Qualified Design ID (QDID)
RX23W Group	134349
RA4W1 Group	134349
RE01B Group	134349
RL78/G1D Group	122047

- Design modification details of RF part (selected from below)
 - Dead copy (C1)
 - Change of pattern layout (Only RF pattern from RF output terminal of IC to antenna (including antenna change)) (C2)
 - Pattern layout change (New PCB pattern including RF part) (C3)
 - Changes of major parts affecting high-frequency characteristics such as quartz crystal unit (C4)
- Preferred date of registration complete

(2). Perform RF-PHY test at the BQTF.

- In the case where design change contents of the RF part are (C1) and (C2)
It is necessary to test two items, Output Power and Receiver Sensitivity.
- In the case where design change contents of the RF part are (C3) and (C4)
Standard 10 items test is required.

(3). Keep of compliance folder.

After product registration, receive and keep the Compliance Folder (A set of certification documents such as Test Report of RF-PHY, ICS / IXIT information, test data, are stored) from BQTF via electronic media (CD-R) or file transfer system.

Note: Apart from RF-PHY testing fee, we need compliance folder creation fee and BQC support fee. Please ask BQTF for cost estimate.

3.2 Registering a device that implements IC / Module

This section describes how to register (Declaration) a device mounting the IC / Module as a Bluetooth product. Purchase of Declaration ID is required for product registration. Refer to "2.2 Purchase of Declaration ID" and perform necessary procedures.

3.2.1 Product registration (Declaration)

After purchasing the Declaration ID, please perform product registration operation on the Bluetooth SIG WEB site as follows.

- (1). After log in to <<https://www.bluetooth.com>>, starting the Launch Studio from the following URL and select the [Getting Started] tab.

<https://launchstudio.bluetooth.com>

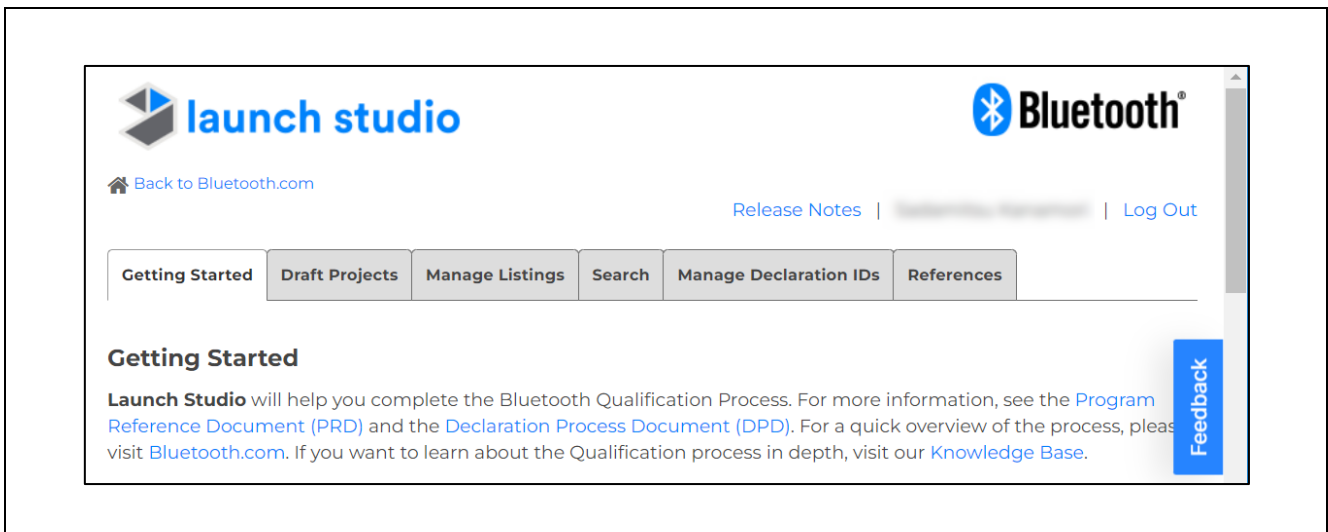


Figure 3-1 [Getting Started] tab

- (2). Click the [Start the Bluetooth Qualification Process with No Required Testing] button at the displayed [Getting Started] tab.

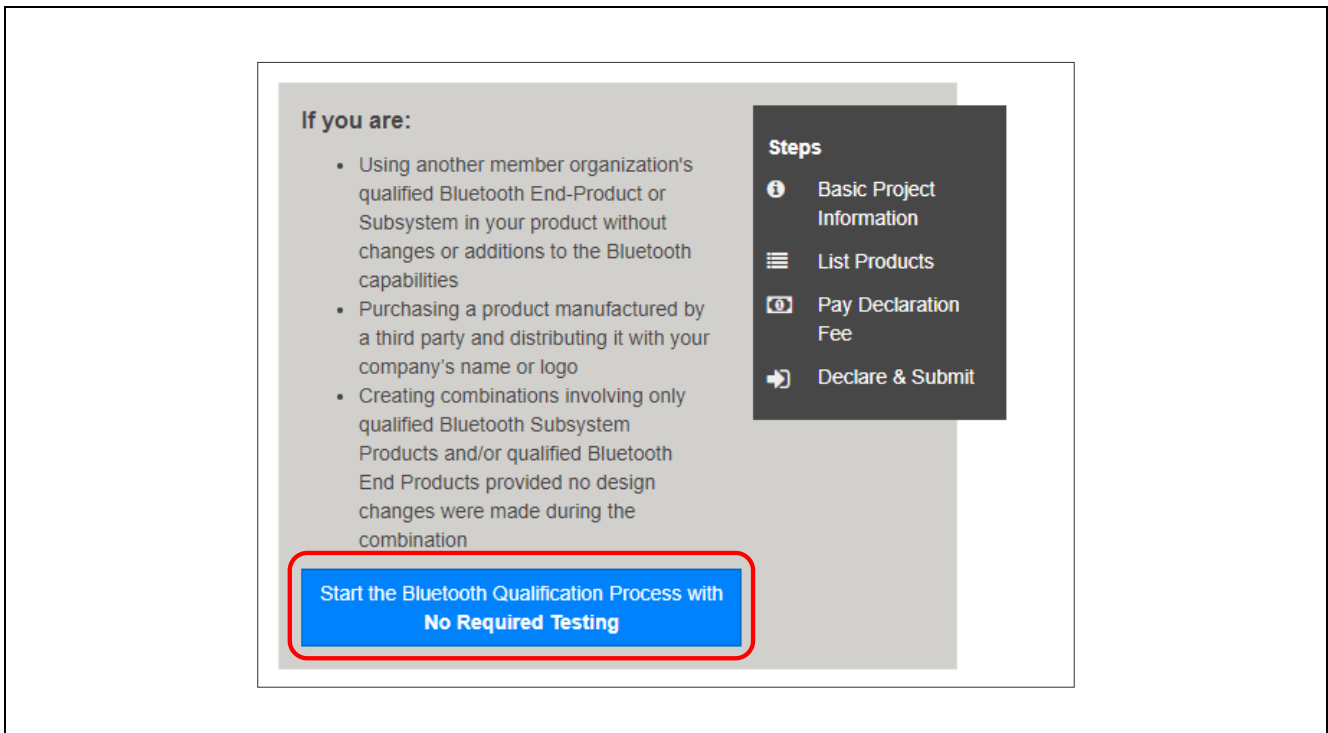


Figure 3-2 [Start the Bluetooth Qualification Process with No Required Testing] button

- (3). Enter the basic information of the project on the displayed page.

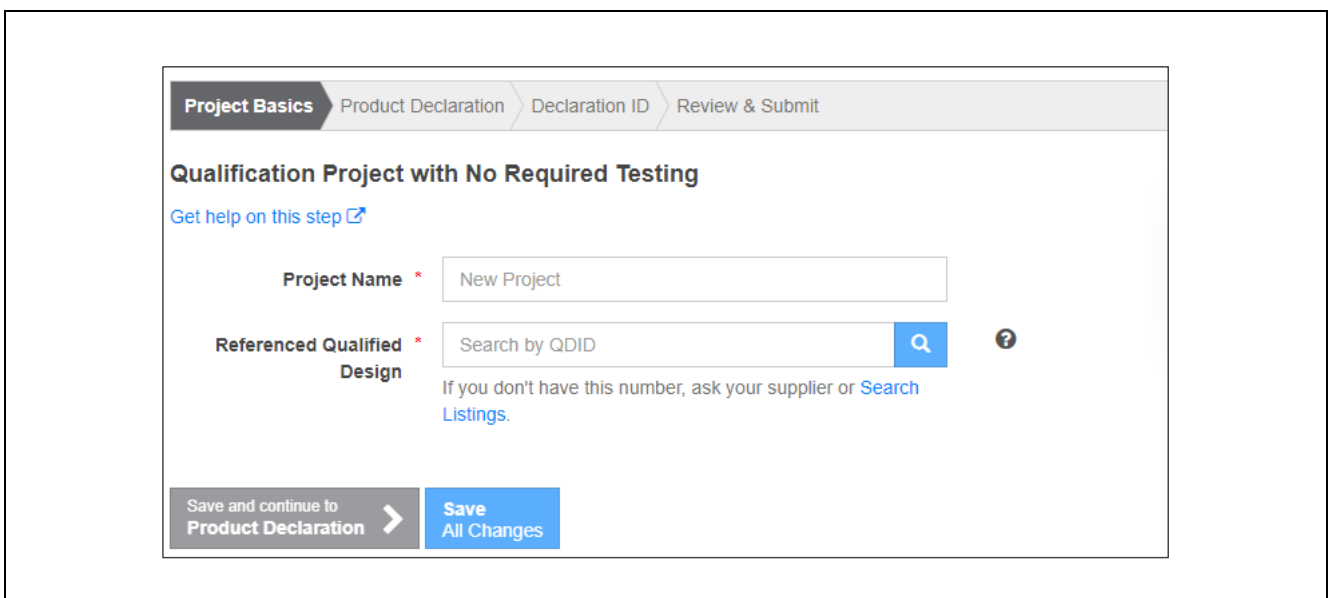


Figure 3-3 [Project Basics] input

- In [Project Name], enter any project name.

- In "Referenced Qualified Design", enter the QDID that corresponds to the Core specifications of the IC / Module Implemented in the product. (Mandatory)

Table 3-2 QDID of Core Specification

IC / Module	Qualified Design ID (QDID)
RX23W Group	134349
RA4W1 Group	134349
RE01B Group	134349
RL78/G1D Group	122047
RX23W Module	134349
RY7011 (RL78/G1D mounted)	122047

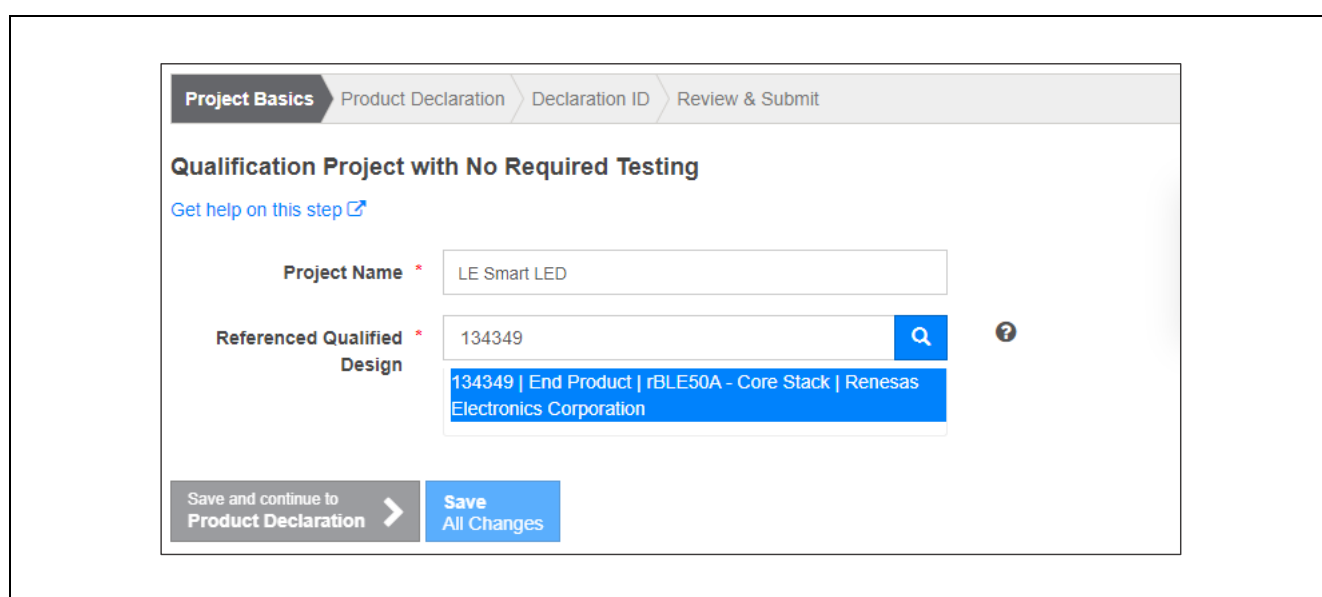


Figure 3-4 Core Specification QDID input example (for RX23W)

- If you want to support the profile specifications developed by the Bluetooth SIG, enter additional the QDID of the Profile Subsystem that contains the applicable profile specifications. (Optional: No input required if does not support profile specifications.)

Table 3-3 QDID of Profile Specification

IC / Module	Qualified Design ID (QDID)
RX23W Group	134484 / 134527 / 199248
RA4W1 Group	134484 / 134527 / 199248
RE01B Group	134484
RL78/G1D Group	97611
RX23W Module	134484 / 134527 / 199248
RY7011 (RL78/G1D mounted)	97611

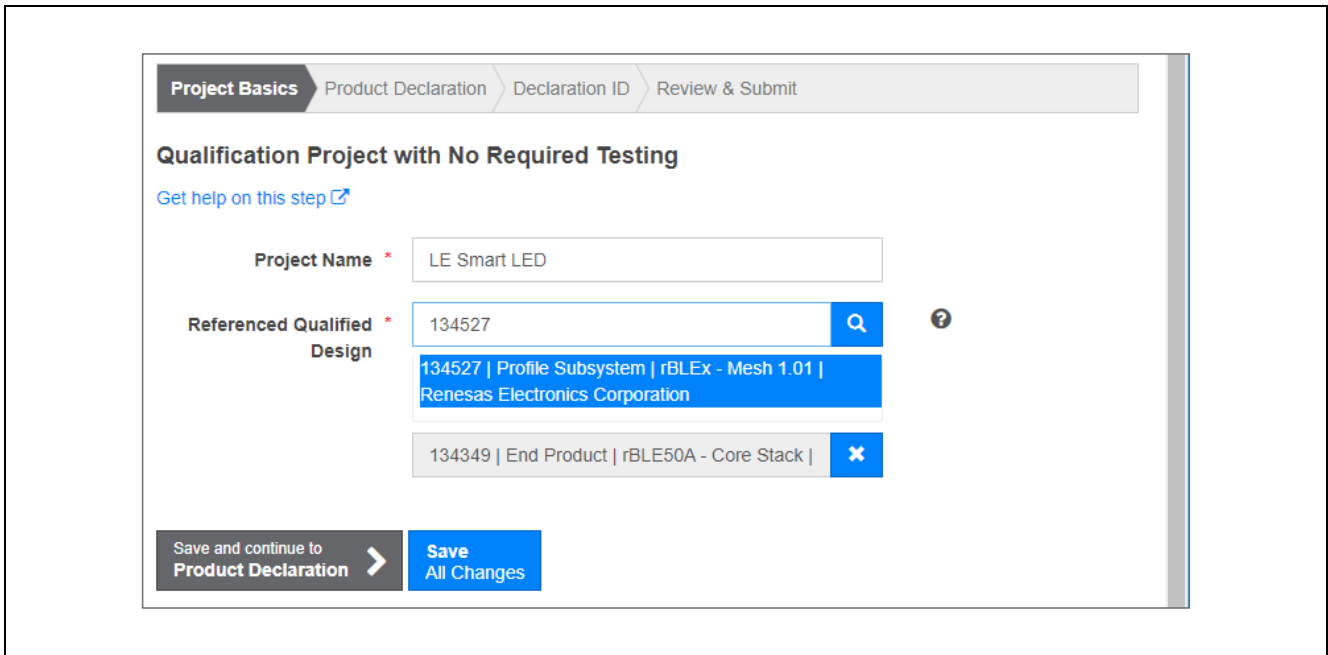


Figure 3-5 Profile Specification QDID input example (for RX23W)

- When input is completed, click the [Save and continue to Product Declaration] button in the lower left.

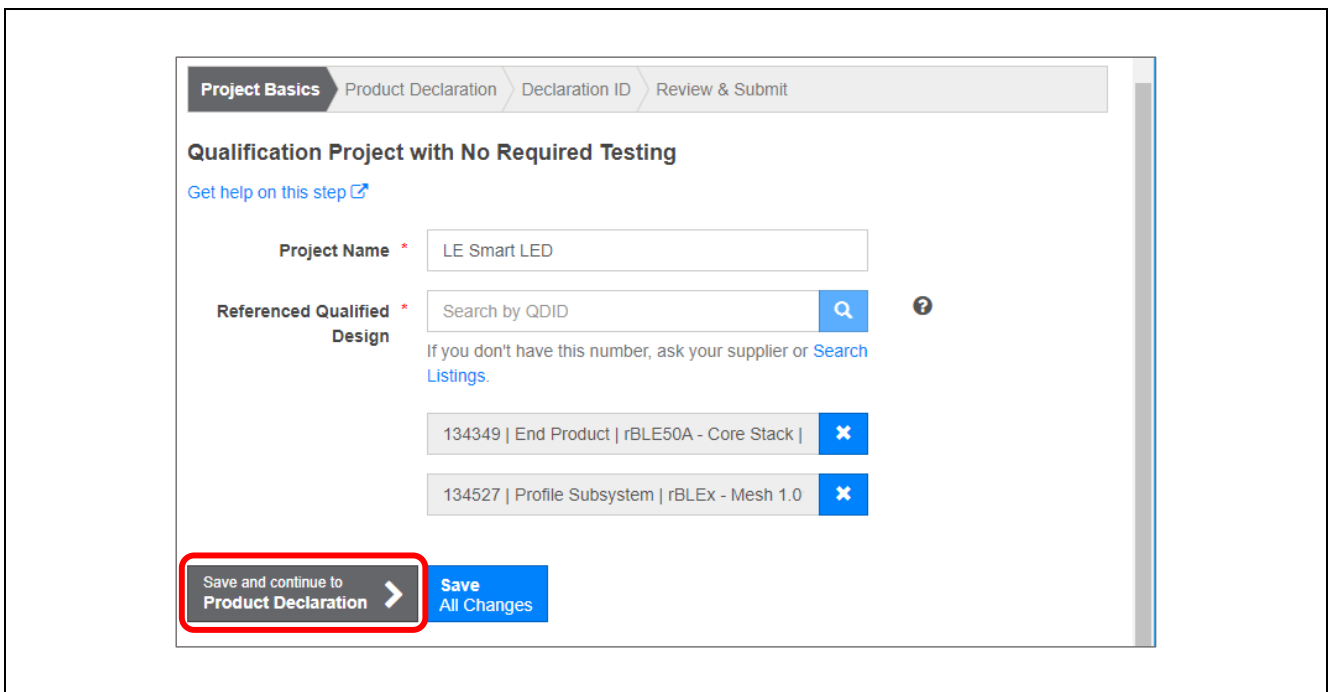


Figure 3-6 [Save and continue to Product Declaration] button

- (4). When the [Product Declaration] page is displayed, set "Listing Date" (Date on which you want to display the registered product in the public list database) in the [Required for submission, YYYY-MM-DD] text box. "Listing Date" can also be set using the calendar displayed by clicking on the text box. Listing Date can be specified up to 90 days later.

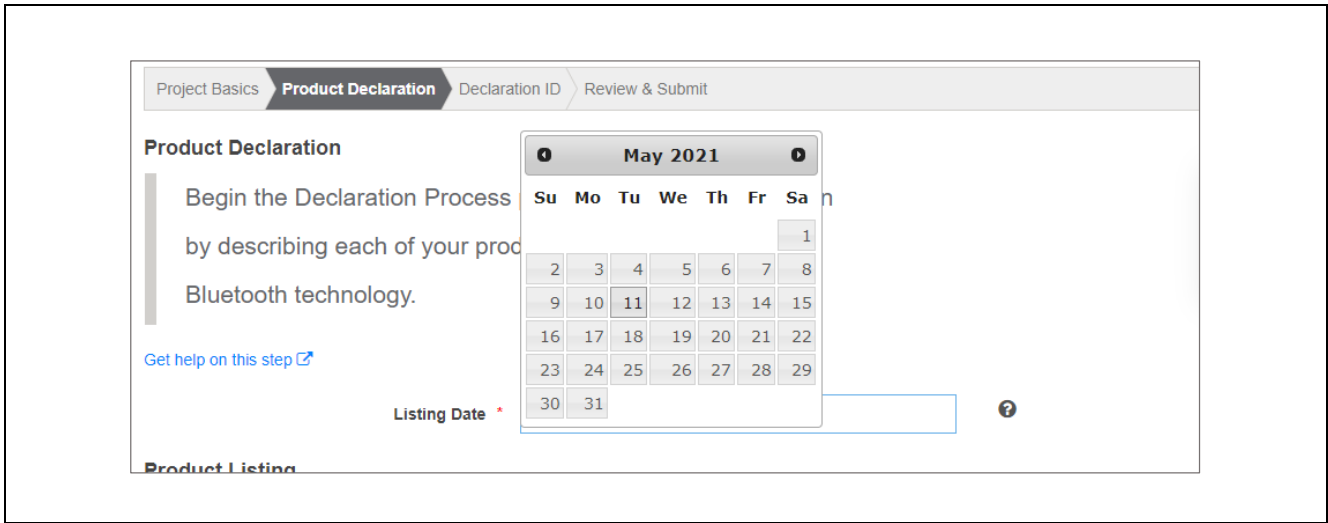


Figure 3-7 [Product Declaration] page

Click [+Add a Product] button displayed at the bottom of the page after setting "Listing Date".

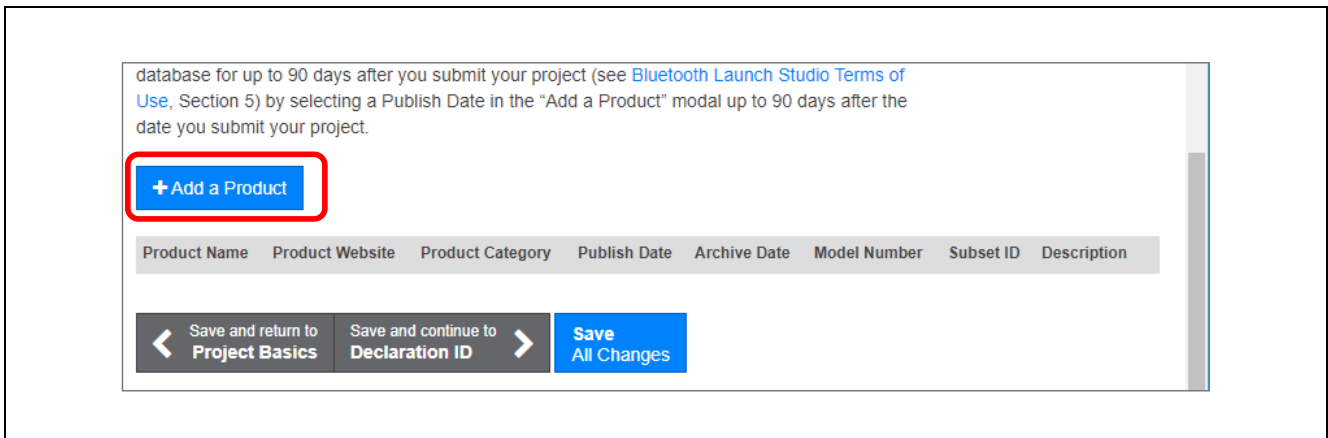


Figure 3-8 [+Add a Product] button

The [Add/Edit products] panel will be displayed, please enter product information. When input is completed, click [Save] button.

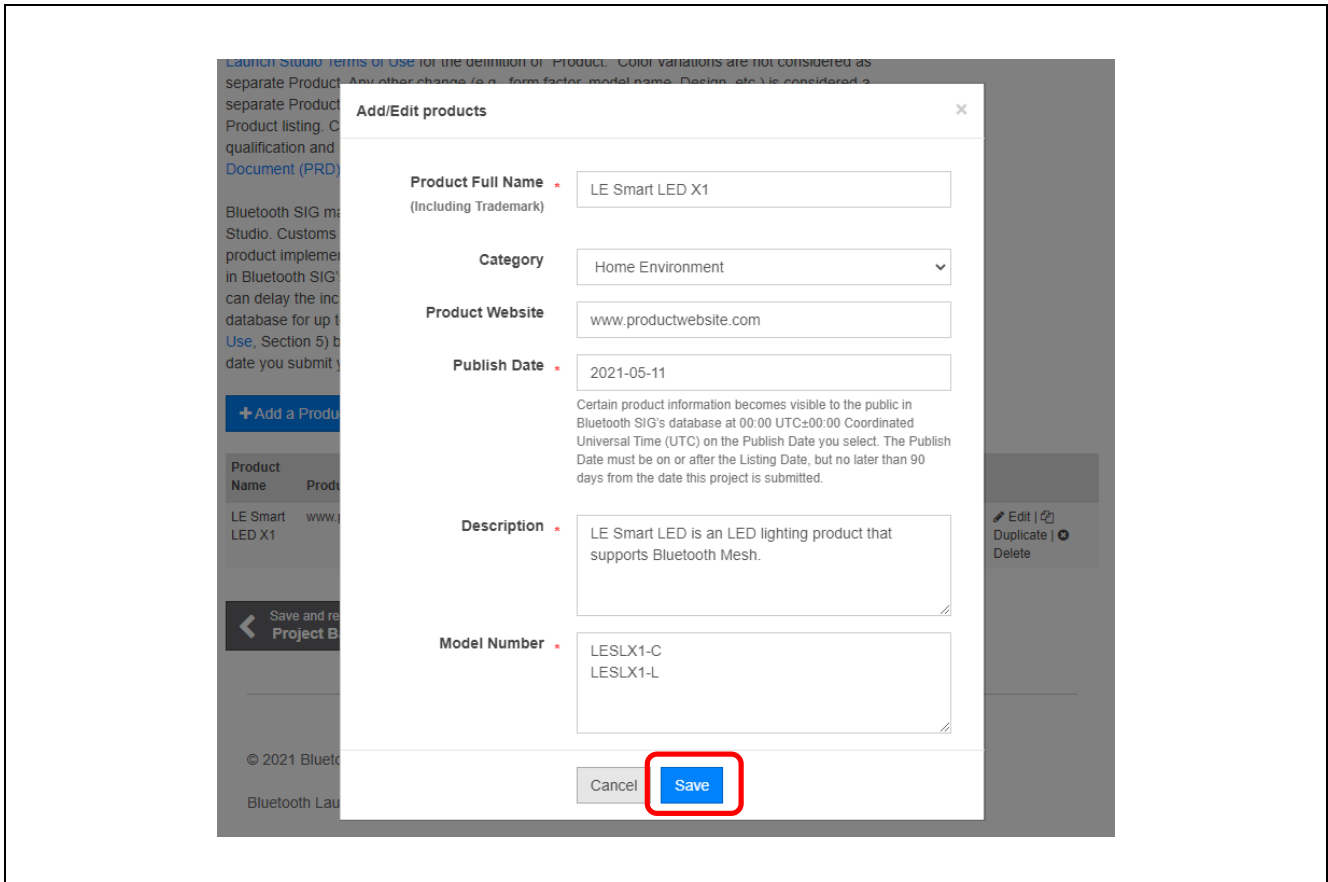


Figure 3-9 [Add/Edit products] panel

- (5). Confirm that the input contents are displayed in the product list and click the [Save and continue to Declaration ID] button.

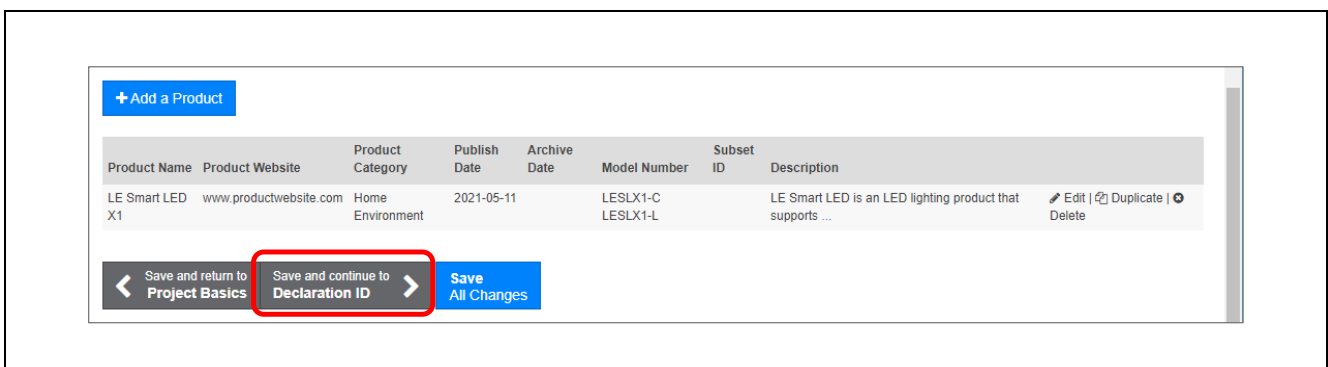


Figure 3-10 Product List

(6). A list of available Declaration IDs is displayed. Select the ID to be used for this product registration and click the [Save and continue to Review] button.

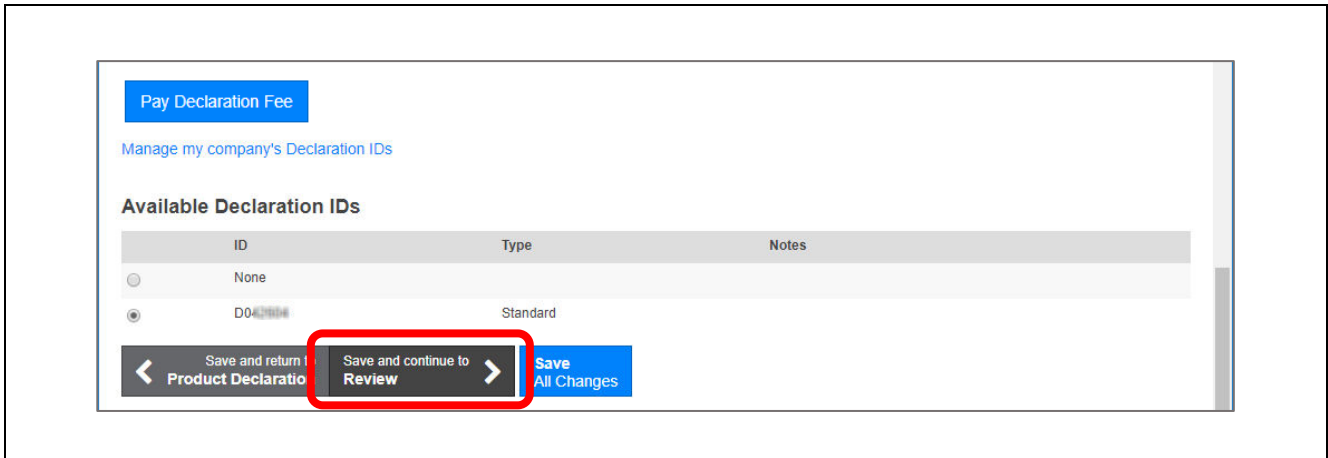


Figure 3-11 [Available Declaration IDs] list

(7). Since the [Review] page is displayed, confirm that the contents of [Project Details] are correct.

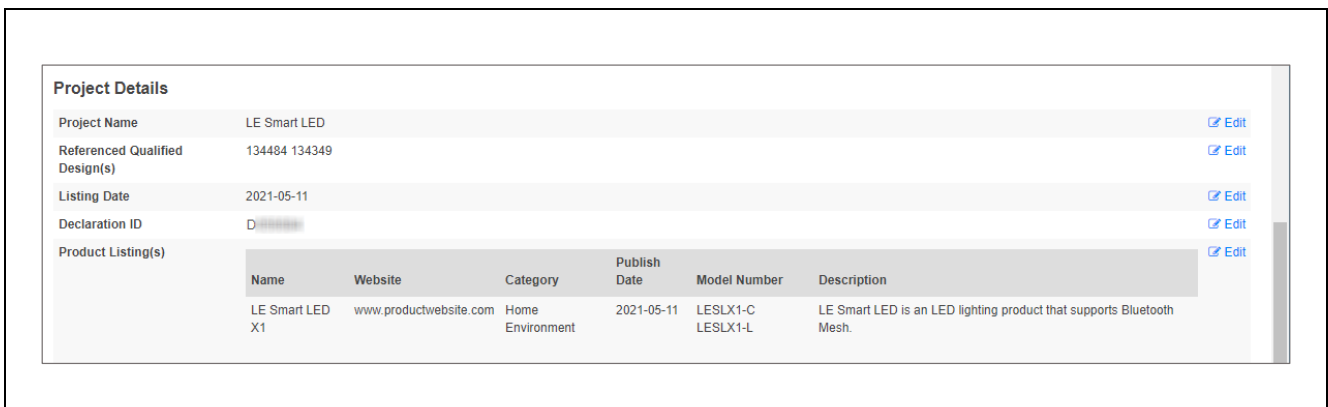


Figure 3-12 [Project Details]

If the contents are correct, check the declaration statement at the bottom of the page and check the check box at the beginning of the declaration statement.

Finally sign the [Signature] text box below the declaration and click the [Signature Confirmed - Complete Project & Submit Product (s) for Qualification] button to complete the online procedure.

The screenshot shows a web form for Bluetooth qualification. At the top, it states: "The Bluetooth Launch Studio Terms of Use, are the Supplier Declaration of Conformity and Declaration of Compliance described in the Program Reference Document (PRD) and Declaration Process Document (DPD)." Below this are five checked checkboxes, each with a red box around the checkmark: 1. "I am authorized by Company to submit all of the information and materials included in this project and all information and materials are true, complete, and accurate." 2. "Company does not, by its governing documents or other applicable law, require more than one signatory, a stamp or seal, or a witnessed signature to be legally bound." 3. "I agree on behalf of Company to contract in English and electronically, and adopt the characters and symbols input in the signature field below as my signature, with the same effect as an ink signature." 4. "The products included in this project are owned by Company and, if marketed or distributed, are done so under a name that uniquely identifies Company as the source of the Product." 5. "The product(s) included in this project and the corresponding Qualified Designs comply with the Bluetooth Launch Studio Terms of Use and the versions of the Bluetooth Specifications referenced in the project." Below the checkboxes is the text: "If any of the foregoing is not correct or you do not agree, you must exit this form without signing." There is a "Signature:" text box with a red box around it. At the bottom are two buttons: "Save & Exit without Submitting" and "Signature Confirmed - Complete Project & Submit Product(s) for Qualification", with the latter button highlighted in blue and having a red box around it. At the very bottom, it says "Submit your project and documentation to the Bluetooth SIG."

Figure 3-13 [Signature Confirmed - Complete Project & Submit Product (s) for Qualification]

Registered products can be confirmed on the Launch Studio's [Manage Listings] tab.

3.2.2 Add a Product

This section describes how to add another device implementing the IC / Module to the list registered (Declared) with "3.2.1".

- (1). After login to <<https://www.bluetooth.com>> using the same account as 3.2.1, to start Launch Studio from the following URL and select the [Manage Listings] tab.

<https://launchstudio.bluetooth.com>

- (2). Click the Declaration ID number of the list created in 3.2.1 to display the [Declaration Details] page.
- (3). Click the [+Add a Product] link on the left side of the page to start the "Add Products" process.
- (4). Click the [+Add a Product] button at the bottom of the displayed page.
- (5). The [Add/Edit products] panel will be displayed, please enter product information. When input is completed, click [Save] button.
- (6). Confirm that the input content is displayed in the product list and click [Continue to Review & Submit] button.
- (7). Since the [Review] page will be displayed, confirm that the contents of [Product Listing (s)] are correct.

If the contents are correct, check the declaration statement at the bottom of the page and check the check box at the beginning of the declaration statement.

Finally sign the [Signature] text box below the declaration statement and click the [Signature Confirmed - Complete Project & Submit Product (s) for Qualification] button to complete the online procedure.

Revision History

Rev.	Date	Description	
		Page	Summary
1.00	Jun.15.16	–	First edition issued
1.10	Jan.15.19	–	Complete revision due to renewal of the Bluetooth SIG website
1.20	Nov.01.19	–	Added information on RX23W Group
1.30	May.07.20	1 3 4 16	<ul style="list-style-type: none"> • Added RA4W1 group to Target Device • Added RA4W to the BLE microcomputer / module column in Table 1-1 • Added RA4W1 to the title line in Table 1-6 • 3.1 (2): "All items" changed to "Standard 10 items"
1.40	May.20.21	–	<ul style="list-style-type: none"> • Complete revision due to renewal of the Bluetooth SIG website • Changed "BLE" to "Bluetooth LE" of the title • Added RE01B Group and RX23W Module to Target Device
1.50	Dec.27.22	3 4 19 24,25	<ul style="list-style-type: none"> • Added QDID 199248 to Table 1-1. • Added QDIDs 134527 and 199248 to Table 1-2. • Removed withdrawn QDID 82194 from Table 1-5. • Added support information for QDID 199248 in Table 1-6. • Removed withdrawn QDID 82194 from Table 3-2. • Table 3-3 updated with latest information • Changed Launch Studio tab name "My Listings" to "Manage Listings"

General Precautions in the Handling of Microprocessing Unit and Microcontroller Unit Products

The following usage notes are applicable to all Microprocessing unit and Microcontroller unit products from Renesas. For detailed usage notes on the products covered by this document, refer to the relevant sections of the document as well as any technical updates that have been issued for the products.

1. Precaution against Electrostatic Discharge (ESD)

A strong electrical field, when exposed to a CMOS device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop the generation of static electricity as much as possible, and quickly dissipate it when it occurs. Environmental control must be adequate. When it is dry, a humidifier should be used. This is recommended to avoid using insulators that can easily build up static electricity.

Semiconductor devices must be stored and transported in an anti-static container, static shielding bag or conductive material. All test and measurement tools including work benches and floors must be grounded. The operator must also be grounded using a wrist strap. Semiconductor devices must not be touched with bare hands. Similar precautions must be taken for printed circuit boards with mounted semiconductor devices.

2. Processing at power-on

The state of the product is undefined at the time when power is supplied. The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the time when power is supplied. In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the time when power is supplied until the reset process is completed. In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the time when power is supplied until the power reaches the level at which resetting is specified.

3. Input of signal during power-off state

Do not input signals or an I/O pull-up power supply while the device is powered off. The current injection that results from input of such a signal or I/O pull-up power supply may cause malfunction and the abnormal current that passes in the device at this time may cause degradation of internal elements. Follow the guideline for input signal during power-off state as described in your product documentation.

4. Handling of unused pins

Handle unused pins in accordance with the directions given under handling of unused pins in the manual. The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of the LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible.

5. Clock signals

After applying a reset, only release the reset line after the operating clock signal becomes stable. When switching the clock signal during program execution, wait until the target clock signal is stabilized. When the clock signal is generated with an external resonator or from an external oscillator during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Additionally, when switching to a clock signal produced with an external resonator or by an external oscillator while program execution is in progress, wait until the target clock signal is stable.

6. Voltage application waveform at input pin

Waveform distortion due to input noise or a reflected wave may cause malfunction. If the input of the CMOS device stays in the area between V_{IL} (Max.) and V_{IH} (Min.) due to noise, for example, the device may malfunction. Take care to prevent chattering noise from entering the device when the input level is fixed, and also in the transition period when the input level passes through the area between V_{IL} (Max.) and V_{IH} (Min.).

7. Prohibition of access to reserved addresses

Access to reserved addresses is prohibited. The reserved addresses are provided for possible future expansion of functions. Do not access these addresses as the correct operation of the LSI is not guaranteed.

8. Differences between products

Before changing from one product to another, for example to a product with a different part number, confirm that the change will not lead to problems. The characteristics of a microprocessing unit or microcontroller unit products in the same group but having a different part number might differ in terms of internal memory capacity, layout pattern, and other factors, which can affect the ranges of electrical characteristics, such as characteristic values, operating margins, immunity to noise, and amount of radiated noise. When changing to a product with a different part number, implement a system-evaluation test for the given product.

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